

SECRET

Approved For Release 2001/11/07 : CIA-RDP78B04747A000300010002-6

R & D CATALOG FORM		DATE
1. PROJECT TITLE/CODE NAME Chip Processor		2. SHORT PROJECT DESCRIPTION Automatic film processor for 4" x 5" cut film.
3. CONTRACTOR NAME [REDACTED]		4. LOCATION OF CONTRACTOR [REDACTED]
5. CLASS OF CONTRACTOR Manufacturer		6. TYPE OF CONTRACT Fixed Price
7. FUNDS	8. REQUISITION NO.	9. BUDGET PROJECT NO.
FY 1964 [REDACTED]	5500-2730-64	NP-R-10
FY 1965 [REDACTED]	10. EFFECTIVE CONTRACT DATE (Begin - end)	11. SECURITY CLASS.
FY 19 \$ [REDACTED]	May 1964 - June 1965	AA - Confidential T - Unclassified W - Unclassified
12. RESPONSIBLE DIRECTORATE/OFFICE/PROJECT OFFICER TELEPHONE EXTENSION DDI/NPIC/P&DS/[REDACTED]		
13. REQUIREMENT/AUTHORITY Effort is being directed toward a photographic chip concept to assist the NPIC analysis. This entails several types of equipment items, one of which is a high-quality processor.		
14. TYPE OF WORK TO BE DONE Engineering Development		
15. CATEGORIES OF EFFORT		
MAJOR CATEGORY	SUB-CATEGORIES	
Reproduction Techniques and Materials	Film	
	Processors/Printers	
16. END ITEM OR SERVICES FROM THIS CONTRACT/IMPROVEMENT OVER CURRENT SYSTEM, EQUIPMENT, ETC. This effort will produce a high-quality chip processor to handle that cut-film exposed in the Chip Printer currently being fabricated.		
17. SUPPORTING OR RELATED CONTRACTS (Agency & Other)/COORDINATION 4" x 5" Chip Printer - [REDACTED]		
18. DESCRIPTION OF INTELLIGENCE REQUIREMENT AND DETAILED TECHNICAL DESCRIPTION OF PROJECT (Continue on additional page if required) Only two suitable automatic chip type film processors are known to have been developed to date. One employed large numbers of rollers configured in layers between which the film passed during the processing cycle. The other used layers of plastic webbing between which the film was passed. Each of these approaches were considered unreliable due to poor tracking and multiple contact with the emulsion and base sides of the film causing extensive surface damage to the film. This effort will result in a chip processor which presents no physical contact.		
19. APPROVED BY AND DATE		
OFFICE Approved For Release 2001/11/07 : CIA-RDP78B04747A000300010002-6	DEPUTY DIRECTOR [REDACTED]	

Declass Review by
NIMA/DOD

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R & D Catalog Form continued...

18. with the film. Each chip is contained in a mount which is picked up by an endless mylar belt and carried through each processing phase and drier. The processor employs the newly developed Super Levitron principle of solution agitation which has proven to be a superior method that provides the ultimate in evenness of development.

25X1A This contract [REDACTED] has been in effect since May 1964 with original delivery scheduled for 15 March 1965. At the time of the Technical Monitor's visit to the contractor's facility in early March, two modifications were requested, these being a new chip immersion method to provide better development control and an increased capacity for the chip magazine. These requested modifications require an extension of the delivery date to 15 June 1965 and additional funding in the amount of [REDACTED]. This information was brought to the attention of TDC on 31 March 1965. 25X1A

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